

Jue Li

List of Publications by Year in descending order

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19
papers

334
citations

933447

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h-index

1058476

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g-index

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all docs

19
docs citations

19
times ranked

246
citing authors

#	ARTICLE	IF	CITATIONS
1	Inhomogeneous deformation and microstructure evolution of Sn-Ag-based solder interconnects during thermal cycling and shear testing. <i>Microelectronics Reliability</i> , 2012, 52, 1112-1120.	1.7	61
2	Reliability of Lead-Free Solder Interconnections in Thermal and Power Cycling Tests. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2009, 32, 302-308.	1.3	41
3	Shock Impact Reliability and Failure Analysis of a Three-Axis MEMS Gyroscope. <i>Journal of Microelectromechanical Systems</i> , 2014, 23, 347-355.	2.5	41
4	Localized recrystallization and cracking of lead-free solder interconnections under thermal cycling. <i>Journal of Materials Research</i> , 2011, 26, 2103-2116.	2.6	39
5	Microstructural Characterization and Mechanical Performance of Wafer-Level SLID Bonded Au-Sn and Cu-Sn Seal Rings for MEMS Encapsulation. <i>Journal of Electronic Materials</i> , 2015, 44, 4533-4548.	2.2	36
6	On the effects of temperature on the drop reliability of electronic component boards. <i>Microelectronics Reliability</i> , 2012, 52, 165-179.	1.7	30
7	A novel impact test system for more efficient reliability testing. <i>Microelectronics Reliability</i> , 2010, 50, 1125-1133.	1.7	14
8	Finite element analyses and lifetime predictions for SnAgCu solder interconnections in thermal shock tests. <i>Soldering and Surface Mount Technology</i> , 2011, 23, 161-167.	1.5	14
9	Reliability assessment of a MEMS microphone under mixed flowing gas environment and shock impact loading. <i>Microelectronics Reliability</i> , 2014, 54, 1228-1234.	1.7	13
10	Dependence of recrystallization on grain morphology of Sn-based solder interconnects under thermomechanical stress. <i>Journal of Alloys and Compounds</i> , 2012, 540, 32-35.	5.5	12
11	Reliability assessment of MEMS devices; A case study of a 3 axis gyroscope. , 2012, , .		9
12	Vertical cracking of Cu-Sn solid-liquid interdiffusion bond under thermal shock test. <i>Materials Today: Proceedings</i> , 2017, 4, 7093-7100.	1.8	6
13	MEMS reliability. , 2020, , 851-876.		6
14	The reliability of component boards studied with different shock impact repetition frequencies. <i>Microelectronics Reliability</i> , 2012, 52, 1445-1453.	1.7	3
15	MEMS Reliability. , 2015, , 744-763.		3
16	Study on thermomechanical reliability of power modules and thermal grease pump-out mechanism. , 2015, , .		3
17	Hyperelastic Property Measurements of Heat-Cured Silicone Adhesives by Cyclic Uniaxial Tensile Test. <i>Journal of Electronic Materials</i> , 2012, 41, 2613-2620.	2.2	2
18	Localized recrystallization and cracking of lead-free solder interconnections under thermal cycling â€“ ERRATUM. <i>Journal of Materials Research</i> , 2012, 27, 978-978.	2.6	1

#	ARTICLE	IF	CITATIONS
19	Finite element modeling for reliability assessment of solder interconnections in a power transistor. , 2012, , .		0